# SENSITRON SEMICONDUCTOR

Powered by Sensitron











# ADVANCED PACKAGING TECHNOLOGY

For use in all Hi-Rel Applications-Space, Military, Medical, Aerospace

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### Advanced Packaging Technology \_\_\_\_\_

Sensitron's Advanced Baseless Packaging Technology is a cost effective packaging solution that generates maximum weight savings with high thermal conductivity and fatigue resistance. Sensitron is positioned as a world leader in the advanced technology industry, with products that are designed, manufactured, tested, and qualified for high reliability applications where size, weight, and reliability are critical to mission success. From engineering design to finished product, our advanced simulation and modeling tools enable us to provide you with innovative product to meet your power solution requirements.

#### **Product Features**

- ✓ Lower profile and light weight
- √ Lowest possible thermal resistance
- √ Higher temperature applications
- ✓ Removes CTE mismatch between substrate & baseplate
- √ Higher reliability
- ✓ Lower cost
- ✓ Automation friendly

#### **Typical Applications**

- ✓ Aircraft Power Electronics
- ✓ Severe Environment
- ✓ Weight Sensitive Applications
- √ Long Cycle Life

#### **Performance Options**

- ✓ Low cost (Alumina)
- ✓ High thermal conductivity (Aluminum Nitride)
- √ High Strength (Silicon Nitride)

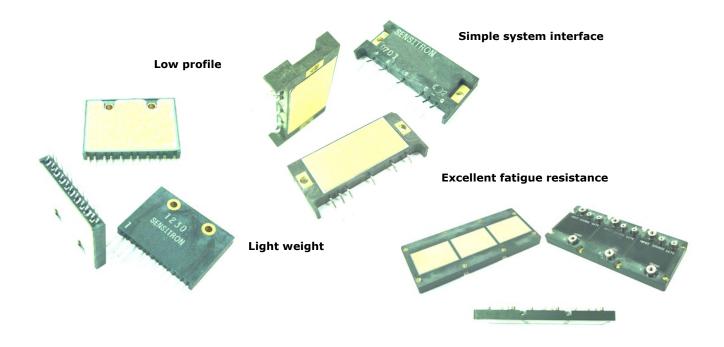
#### **Attribute Comparison by Compositon**

	Advanced	Traditional			
	Baseless Packaging Technology	Copper Baseplate	AlSiC Baseplate	Aluminum Baseplate	IMS Technology (Al)
Thermal Performance					
Thermal resistance index	0.4	1.0	1.1	1.2	1.4
Max usable temperature	200°C	150°C	150°C	150°C	150 °C
Fatigue resistance	superior	fair	good	poor	excellent
Flatness (per inch)	<=0.003	>=0.005	N/A**	>= 0.005	>= 0.005
Cost factor	\$	\$\$\$\$	\$\$\$\$\$	\$\$\$	\$\$
Weight index	0.2	1.0	0.5	0.5	0.5
Typical package height (for a comparable module)	0.2 inch	0.325 inch	0.37 inch	0.325 inch	0.325 inch

<sup>\*\*</sup> Bottom surface of AlSiC baseplates is normally designed to have curvature.



## Advanced Packaging Technology \_\_\_

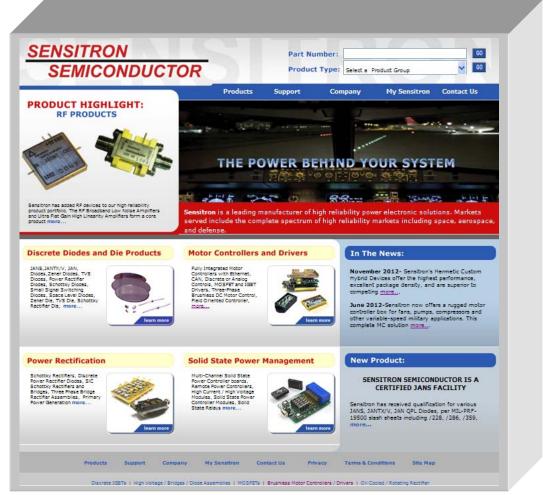


#### **Baseless Material Options & Performance Characteristics**

Characteristic		<i>Alumina</i> Al2O3, 96%	Aliminum Nitride AlN	Silicon Nitride Si3N4*
	Thermal performance			
ical	color	white	gray	pink
mechanical physical	density	3.8 g/cc	3.3 g/cc	3.2 g/cc
	flexural strength	320 MPa	290 Mpa	650 MPa
	elastic modulus	300 GPa	330 GPa	300 GPa
	Fracture toughness	3.5 MPa-m <sup>1/2</sup>	3.5 MPa-m <sup>1/2</sup>	6.7 MPa-m <sup>1/2</sup>
ıal	CTE	6.4 um/m-C	4.7 um/m-C	2.5 um/m-C
thermal	thermal coductivity	25 W/m-K	180 W/m-K	90 W/m-K
th	heat capacity	880 J/kg-C	740 J/kg-C	700 J/kg-C

<sup>\*</sup>Si3N4: higher strength and fracture toughness, better CTE match with silicon.





Visit online at: www.sensitron.com

**About Sensitron:** Sensitron is a leading manufacturer of high reliability power electronic solutions including motor controllers, diodes, smart power management and conversion, voltage protection components and embedded boards, with over 40 years heritage serving space, aerospace, and defense markets.